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FINAL PRODUCT/PROCESS CHANGE NOTIFICATION Generic Copy

Issue Date: December 20, 2006

SUBJECT: ON Semiconductor Final Product/Process Change Notification #15692

TITLE: Addition of Alternate Die source for LM2576-ADJ Family

PROPOSED FIRST SHIP DATE: 20-Feb-2007

AFFECTED CHANGE CATEGORY(S): Wafer Die Source

AFFECTED PRODUCT DIVISION(S): Analog Products

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or Alan Garlington <alan.garlington @onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office or Ota Miklas <ota.miklas@onsemi.com>

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or Matt Kas <matt.kas@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 60 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

This is the Final PCN to Initial PCN 15639 available at <u>www.onsemi.com</u> announcing an alternate mask set has been qualified for the LM2576-ADJ family of devices. This new die has been fully qualified and will be used to supplement capacity requirements on the primary LM2576 die for the adjustable output voltage series only. There will be no change in the data sheet electrical parameters and all part functionalities remain the same.

At the expiration of the Final Product Change Notice, either die may be used to satisfy demands for this part family.

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RELIABILITY DATA SUMMARY:

Reliability Test Results:

Test		Conditions	Results				
HTOL	High Temp Op Life	Ta = 98C, Tj = 150C 504 Hrs	0/80				
LU	Latch Up	Class I 25C Class II 85C	Pass Pass				
ESD	Electro-static Discharge	Human Body Model (HBM)	Pass 2KV				
ESD	Electro-static Discharge	Machine Model (MM)	Pass 200V				
ESD	Electro-static Discharge	Charge Device Model (CDM)	Pass 1250V				
* LU and ESD completed on 2 lots							

ELECTRICAL CHARACTERISTIC SUMMARY:

Major Parameters -	Wafer lot	Wafer lot – SF88572				
Test	Condition	Unit	Mean	S.D.	Min.	Max.
Feedback Voltage	Vin = 12V, II = .5A	V	1.232	.002	1.226	1.236
Quinescent Current	V = 40V	ma	5.43	.053	5.29	5.34
Stby Quin. Current	ua	48	1.49	44	50	
Oscillator Freq		KHz	55.2	1.15	50.8	56.4
Current Limit		А	6.04	.073	5.85	6.17

CHANGED PART IDENTIFICATION:

Changed part identification will be done by Date Code. Parts assembled on or after date code 0709 may utilize the new die source.

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AFFECTED DEVICE LIST PART

LM2576D2T-ADJ LM2576D2T-ADJG LM2576D2T-ADJR4 LM2576D2T-ADJR4G LM2576T-ADJ LM2576T-ADJG LM2576TV-ADJ LM2576TV-ADJ LM2576TV-ADJG